

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S170	2143	(438/208,107,109,4,928,915,187,209,203,86,195).CCLS.	USPAT; USOCR	OR	OFF	2005/07/28 15:10
S171	6	S170 and "MCM type"	US-PGPUB; USPAT	OR	ON	2005/07/28 15:12
S172	98	S170 and "die bonding"	US-PGPUB; USPAT	OR	ON	2005/07/28 15:29
S173	3	S170 and "compact semiconductor device"	US-PGPUB; USPAT	OR	ON	2005/07/28 15:39
S174	139	S170 and "mcm"	US-PGPUB; USPAT	OR	ON	2005/07/28 15:41
S175	2824	(257/723,787).CCLS.	USPAT; USOCR	OR	OFF	2005/07/29 12:32
S176	52	S175 and "insulation film"	US-PGPUB; USPAT	OR	ON	2005/07/29 12:41
S177	0	S176 and "single-layer"	US-PGPUB; USPAT	OR	ON	2005/07/29 12:33
S178	11	S176 and "die bonding"	US-PGPUB; USPAT	OR	ON	2005/07/29 12:34
S179	2140	(257/758,759).CCLS.	USPAT; USOCR	OR	OFF	2005/07/29 15:36
S180	21	S179 and "die bonding"	US-PGPUB; USPAT	OR	ON	2005/07/29 15:41
S181	239	S179 and insulation with film	US-PGPUB; USPAT	OR	ON	2005/07/29 16:04
S182	15	((("4630096") or ("4746960") or ("4827328") or ("4860166") or ("4866508") or ("4878991") or ("4884122") or ("4894115") or ("4907062") or ("4933042") or ("5049980") or ("5091769") or ("5111278") or ("5144747") or ("5250843"))).PN.	USPAT; USOCR	OR	OFF	2005/07/29 16:09
S183	1947	(257/758).CCLS.	USPAT; USOCR	OR	OFF	2005/08/01 08:39
S184	5189	((257/685,687,90,723,787) or (438/107,118)).CCLS.	USPAT; USOCR	OR	OFF	2005/08/01 08:40
S186	404	S184 and (remove or removal) with substrate	US-PGPUB; USPAT	OR	ON	2005/08/01 09:39
S187	133	S184 and substrate adj1 (remove or removal or removed)	US-PGPUB; USPAT	OR	ON	2005/08/01 10:43
S188	6	S184 and Si adj substrate adj1 (remove or removal or removed)	US-PGPUB; USPAT	OR	ON	2005/08/01 10:44
S189	1	("6159767").PN.	USPAT; USOCR	OR	OFF	2005/08/01 15:50